

Enhancing guard-ring protection structures for the next generation of radiation-hard thin silicon particle detectors

T. Croci^{(1,*), A. Fondacci^{(4,1), R. White^{(5), A. R. Altamura^{(5), M. Durando^{(6), S. Galletto^{(6), G. Paternoster^{(7), M. C. Vignali^{(7), M. Boscardin^{(7), R. Arcidiacono^{(8,5), N. Cartiglia^{(5), F. Moscatelli^{(2,1), D. Passeri^{(3,1), M. Ferrero^{(5), V. Sola^{(6,5) and A. Morozzi⁽¹⁾}}}}}}}}}}}}}}}



- 1) Istituto Nazionale di Fisica Nucleare (INFN), Perugia, Italy.
- 2) Istituto Officina dei Materiali (IOM) CNR, Perugia, Italy.
- 3) Dipartimento di Ingegneria, Università di Perugia, Perugia, Italy.
- 4) Dipartimento di Fisica, Università di Perugia, Perugia, Italy.
- 5) Istituto Nazionale di Fisica Nucleare (INFN), Torino, Italy.
- 6) Dipartimento di Fisica, Università di Torino, Torino, Italy.
- 7) Fondazione Bruno Kessler (FBK), Trento, Italy.
- 8) Dipartimento di Scienze del Farmaco, Università del Piemonte Orientale, Novara, Italy.



(*) tommaso.croci@pg.infn.it

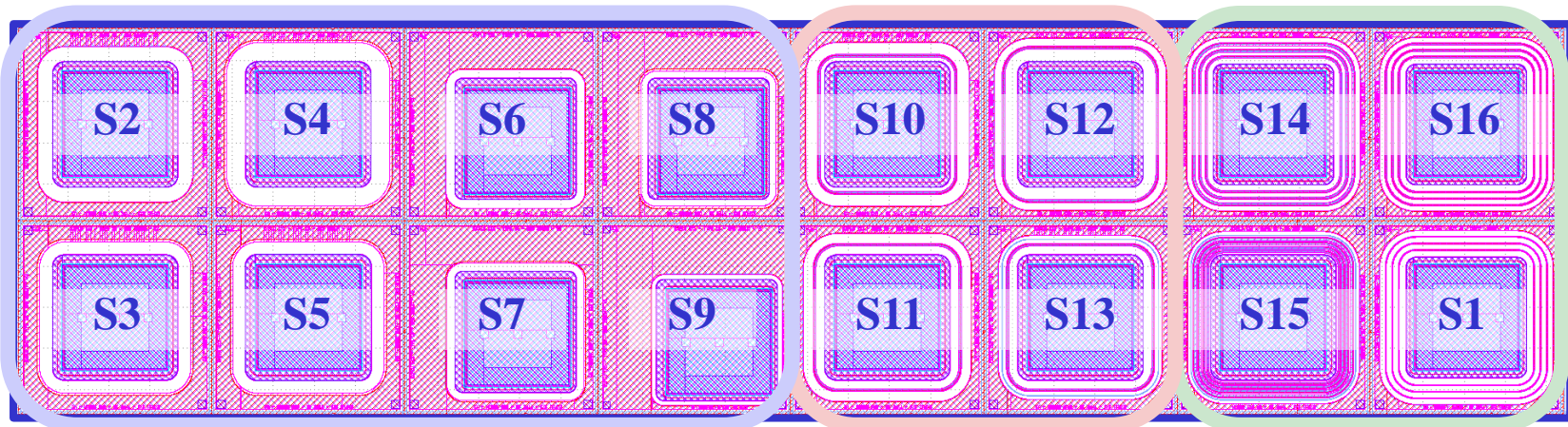
Motivations

- ✓ Developing high performing silicon detectors for particle tracking in the next generation of high-energy physics experiments at future colliders (e.g. HL-LHC, FCC) able to operate efficiently up to very high fluences, $\Phi \sim 1 \times 10^{17} \text{ 1 MeV } n_{\text{eq}}/\text{cm}^2$.
 - ✓ To sustain high voltage values with minimum leakage current injection into the core region of the sensor, the design and optimization of the Guard-Ring (GR) protection structure is crucial, especially when small substrate thicknesses are used.
 - ✓ In a recent R&D batch produced at FBK in the framework of the "exFlu" project, different optimisation studies of GR structures for p-type thin substrates (45, 30, 20 and 15 μm) up to high fluences ($2.5 \times 10^{15} \text{ 1 MeV } n_{\text{eq}}/\text{cm}^2$) have been addressed.
 - ad-hoc advanced Technology CAD (TCAD) modelling of the different GR design strategies, accounting for the radiation-induced damage effects (bulk + surface);
 - extensive test campaign on these GR structures, both before and after irradiation.
- Validation of the development framework and evaluation of the impact of the various GR design options on their performance, both before and after irradiation.

Simulations: p-type substrate

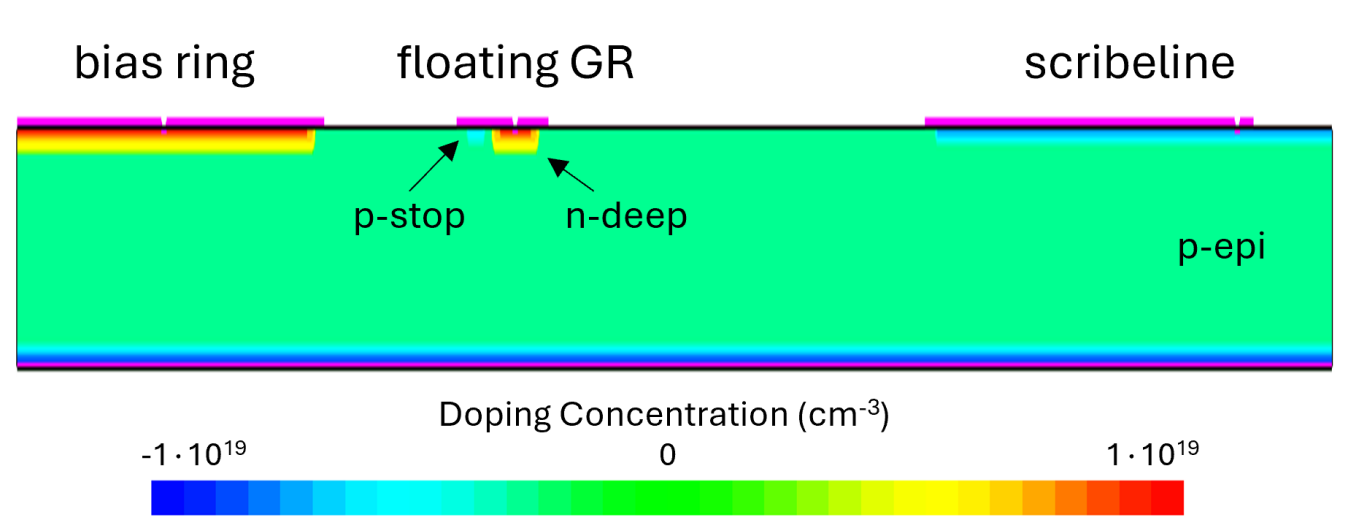
"EXFLU1" R&D batch, FBK

Shot with GR designs (i.e. S1, S2, etc...)

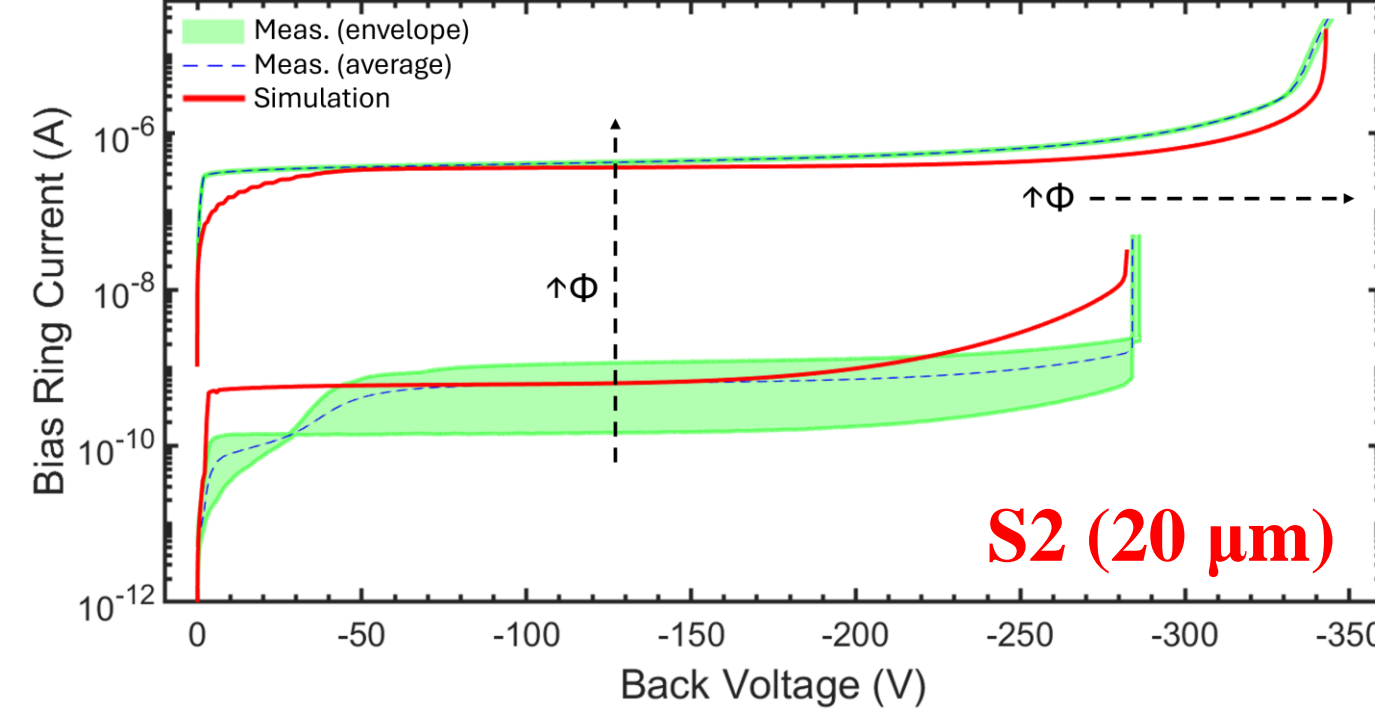


- ✓ Four substrate thicknesses: 45, 30, 20 and 15 μm
- ✓ Irradiation campaign with neutrons at the JSI TRIGA reactor (Ljubljana, Slovenia), Fluences (Φ): 8-15-25E14 1 MeV $n_{\text{eq}}/\text{cm}^2$

Layout of a GR structure (e.g. GR1)



Current-Voltage vs Fluence (1.5E15 $n_{\text{eq}}/\text{cm}^2$) [1]

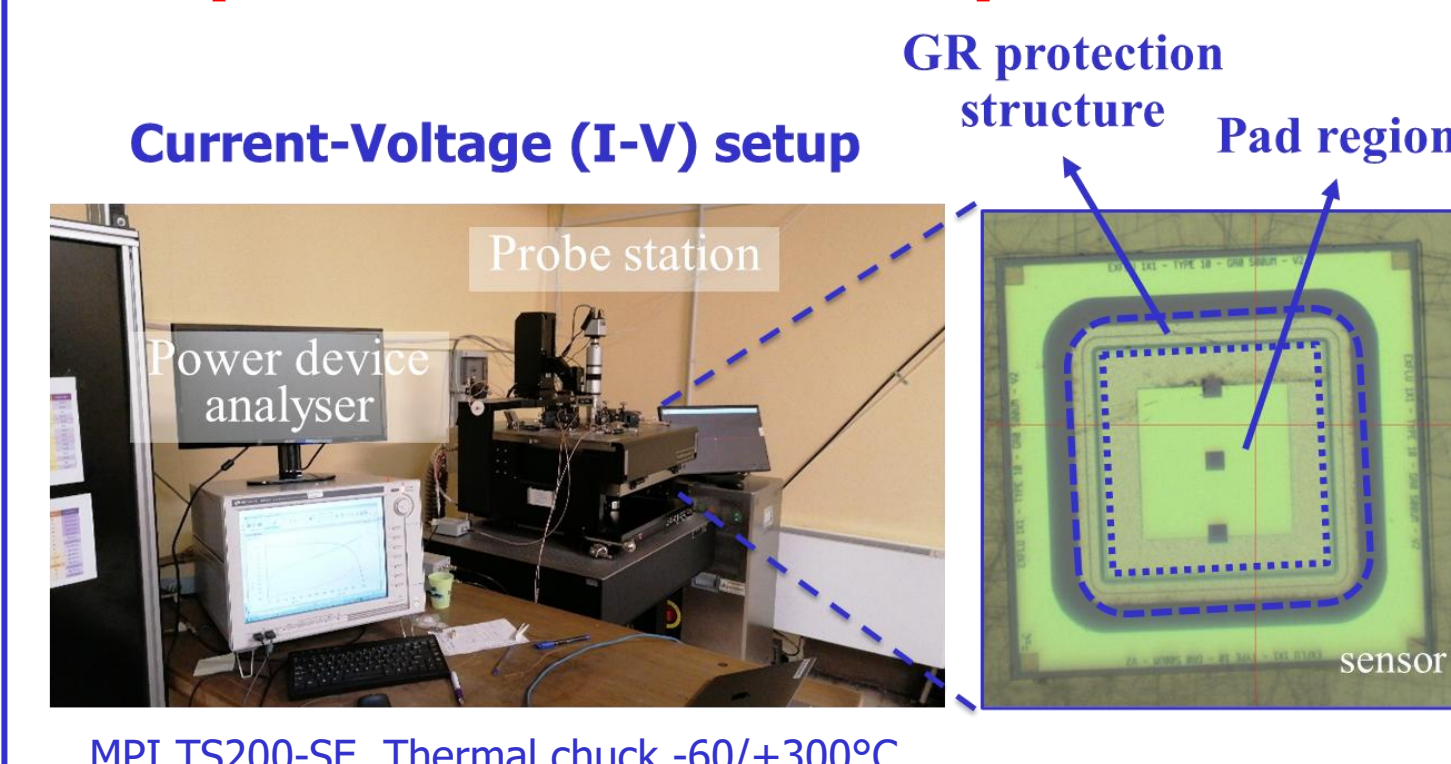


- [1] T. Croci *et al.*, NIM, A 1069 (2024) 169801.
- [2] P. Asenov *et al.*, NIM, A 1040 (2022) 167180.

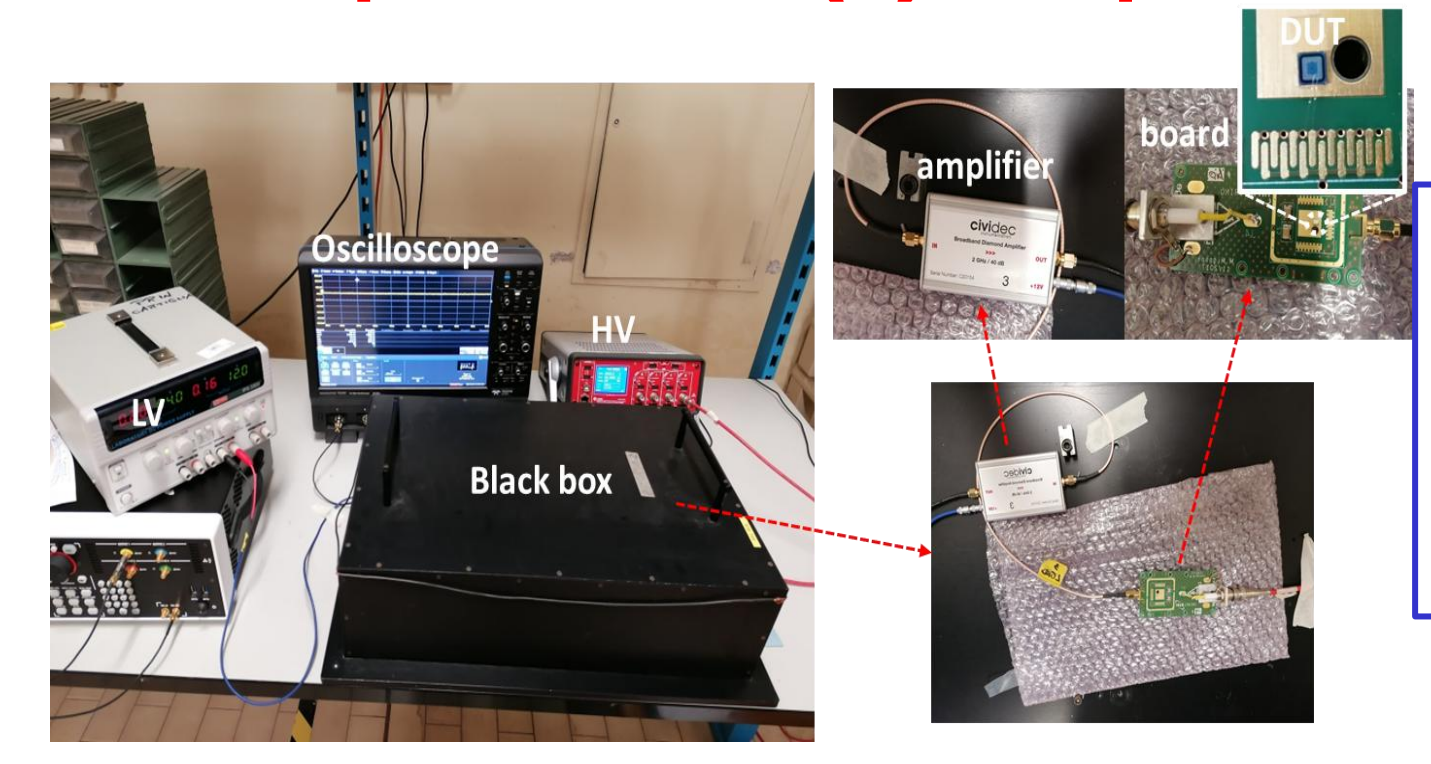
- ✓ GR0: no floating GRs, varying
 - edge region size
 - void region size (i.e., scribble)
 - metal overhang
- ✓ GR1: 1 floating GR, varying
 - floating GR position
- ✓ GR3: 3 floating GRs, using one or both of:
 - single n-deep implant
 - single p-stop implant

Measurements: p-type substrate

Temperature-controlled probe station



Popcorn noise (*) setup



Current-Voltage (I-V) setup

GR protection structure

Pad region

Probe station

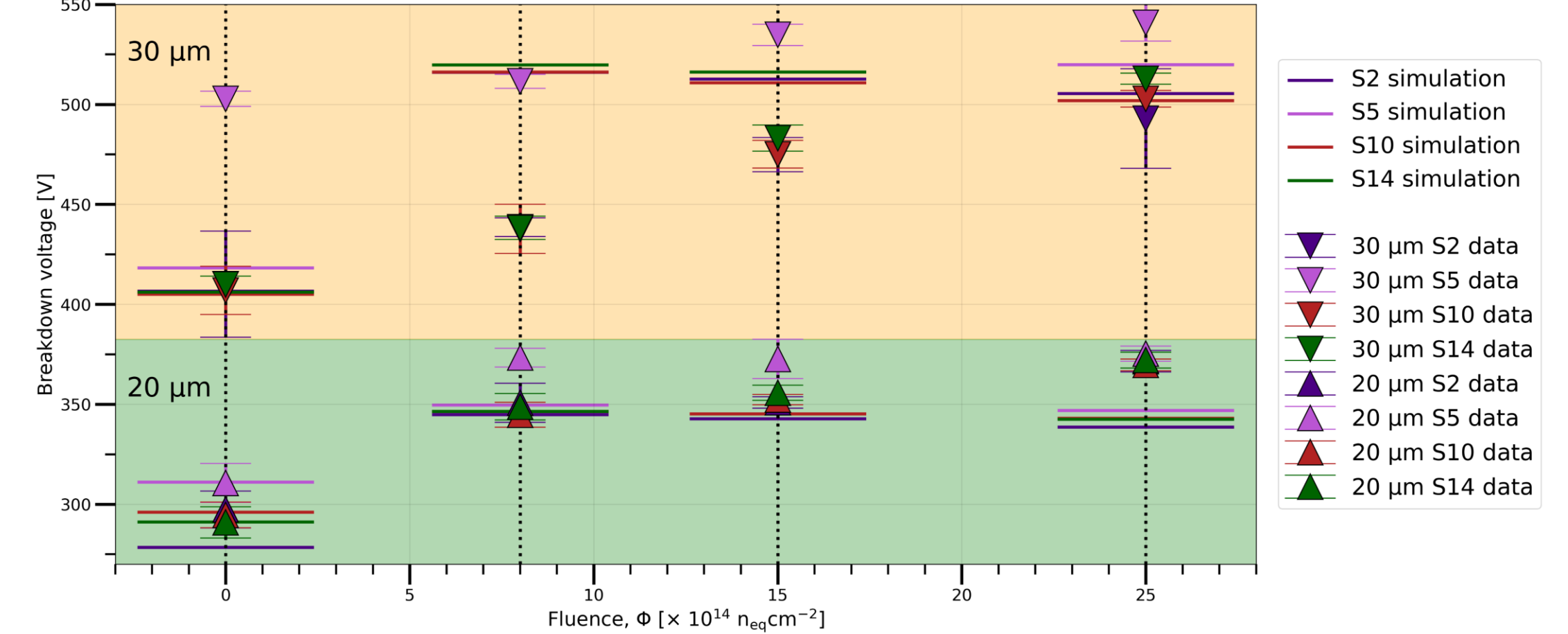
power device analyser

MPI TS200-SE, Thermal chuck -60/+300°C

"Perugia Modified Doping" TCAD radiation damage model [2]

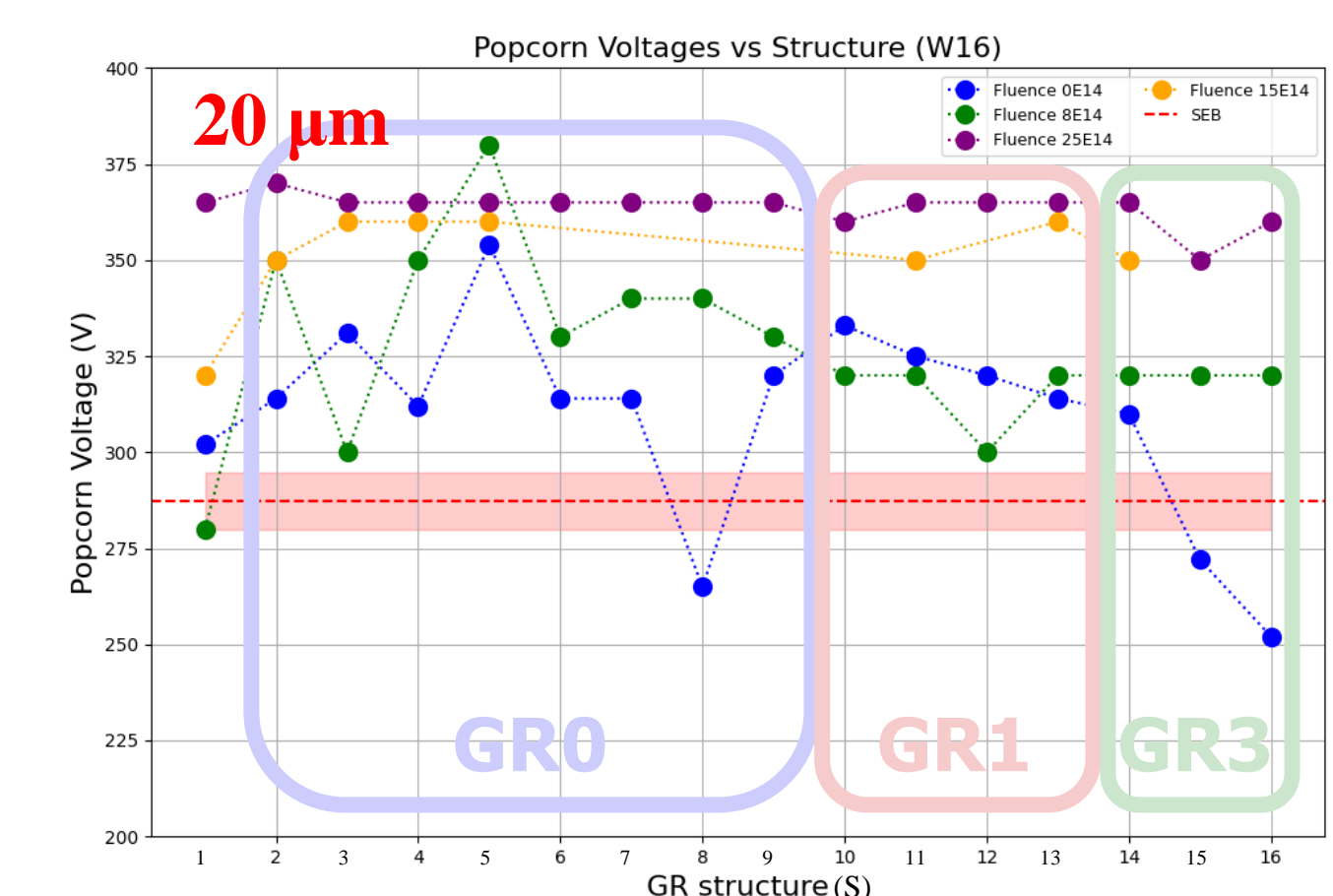
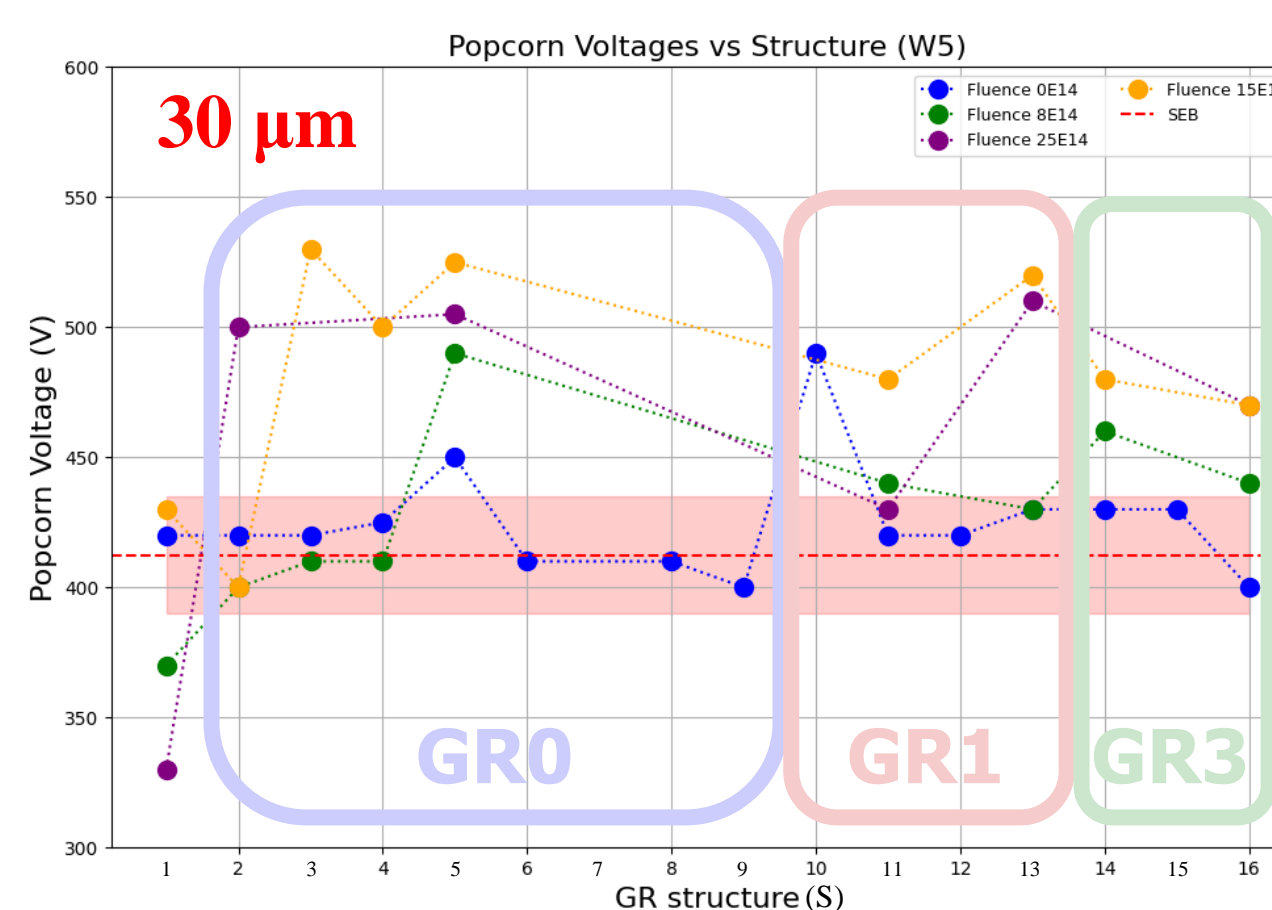
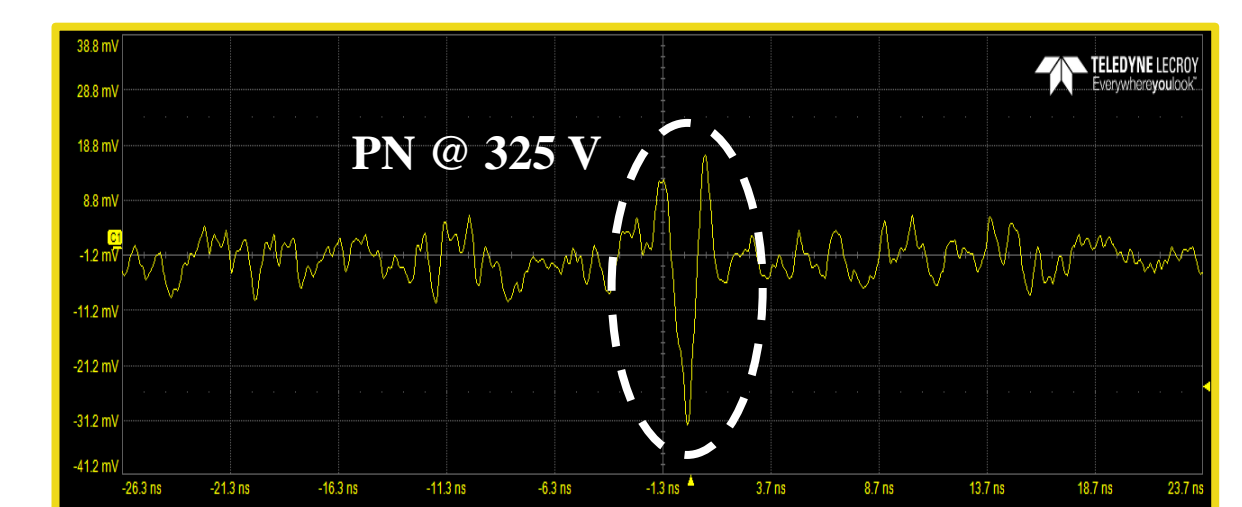
GOOD AGREEMENT

Breakdown voltage (mean value) vs Fluence



(*) Popcorn noise (PN):

type of noise in detectors characterized by random and sudden peaks in the output signal, which can exhibit significant amplitude in the absence of external stimuli.

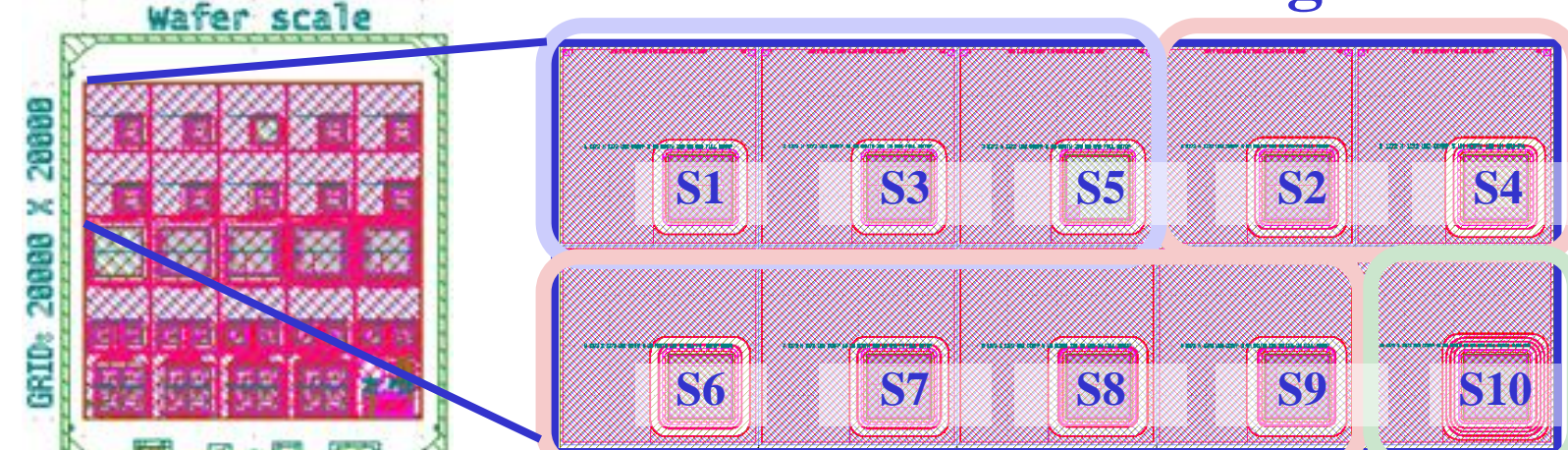


when $\uparrow \Phi \rightarrow \uparrow V_{\text{PN}} (\approx V_{\text{BD}})$ well beyond the SEB limit [3].
Not all the GR structures show PN (S1 is typically the worst GR design).
[3] M. Ferrero *et al.*, 43rd RD50 Workshop, CERN (2023).

Simulations: n-type substrate

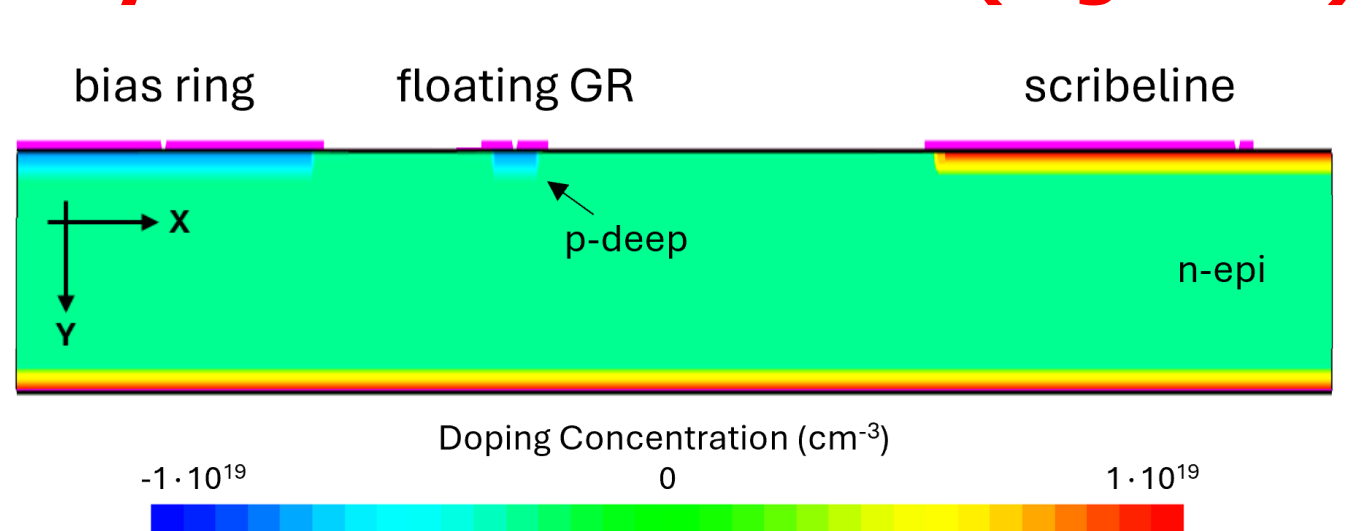
"NLGAD" R&D batch, FBK (ongoing production)

Shot with GR designs

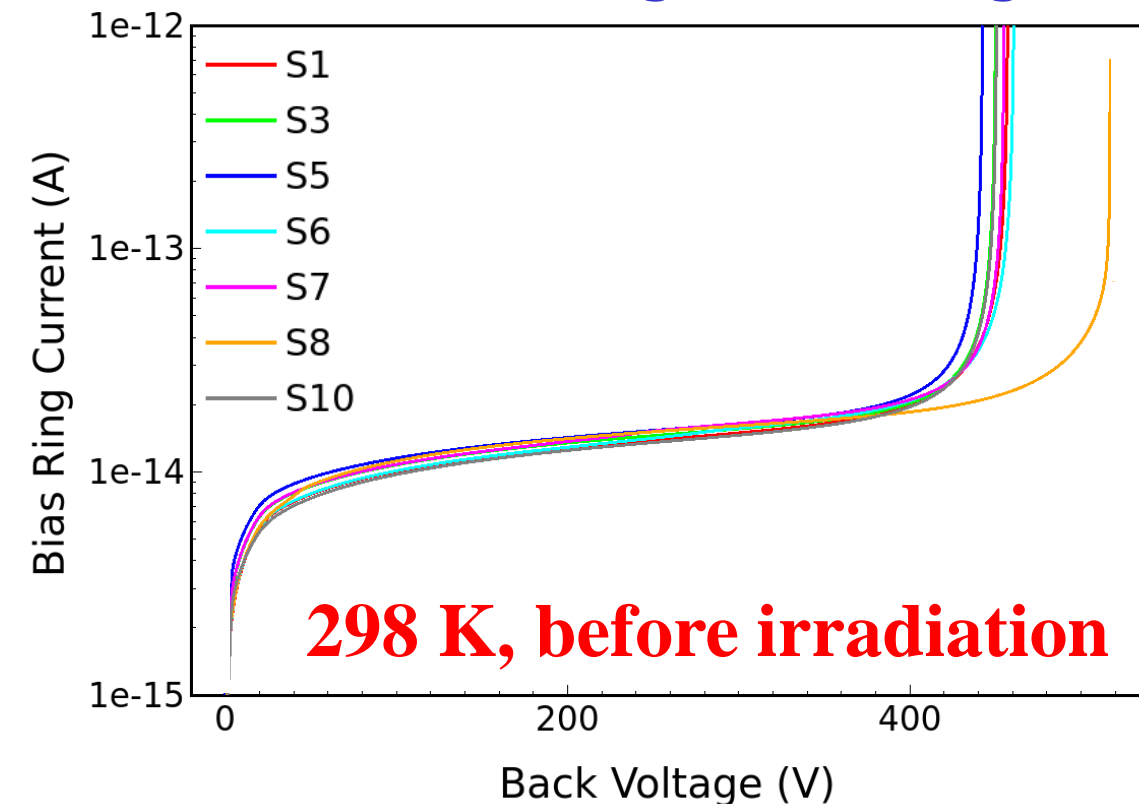


- ✓ Substrate thickness: 55 μm

Layout of a GR structure (e.g. GR1)

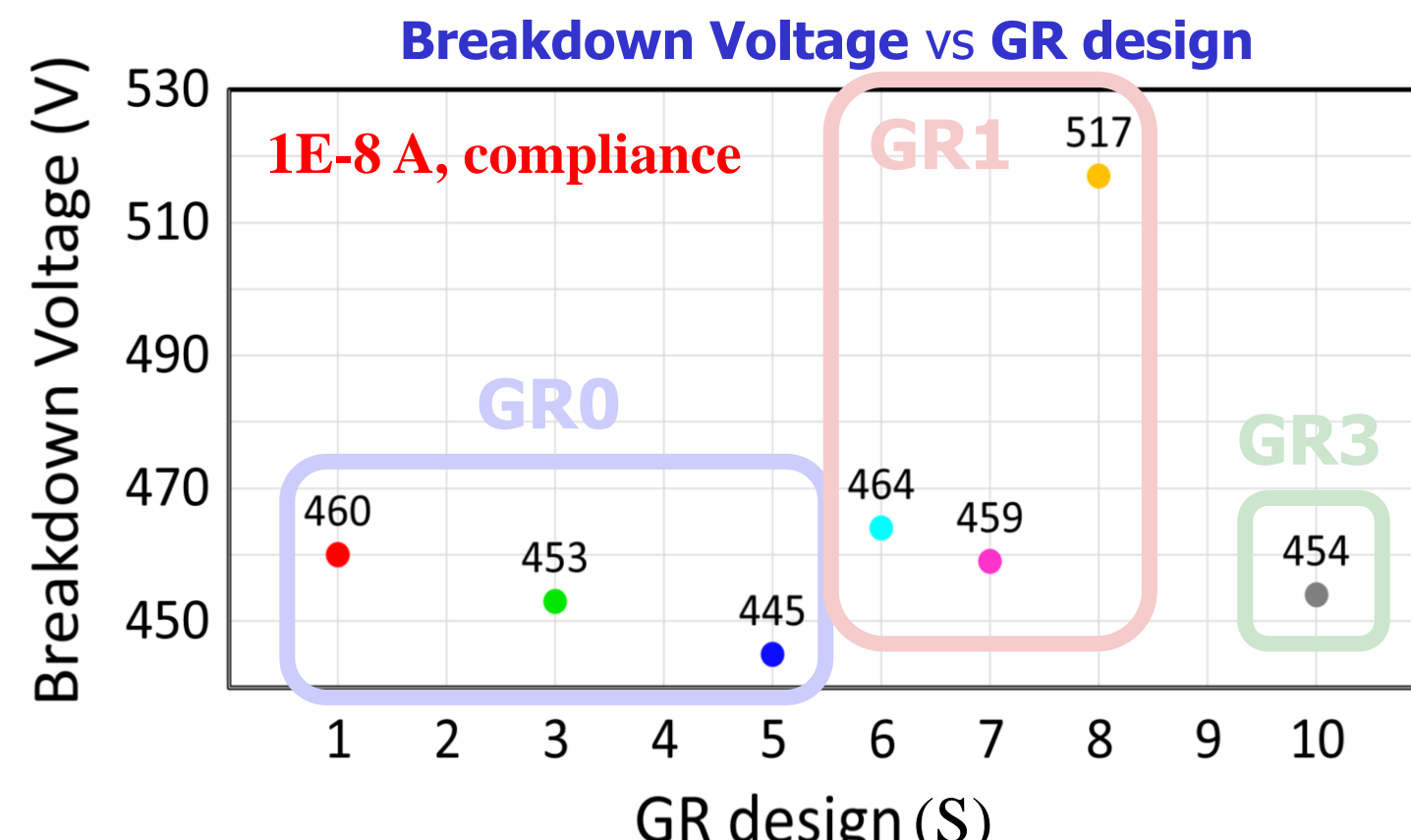


Current-Voltage vs GR design



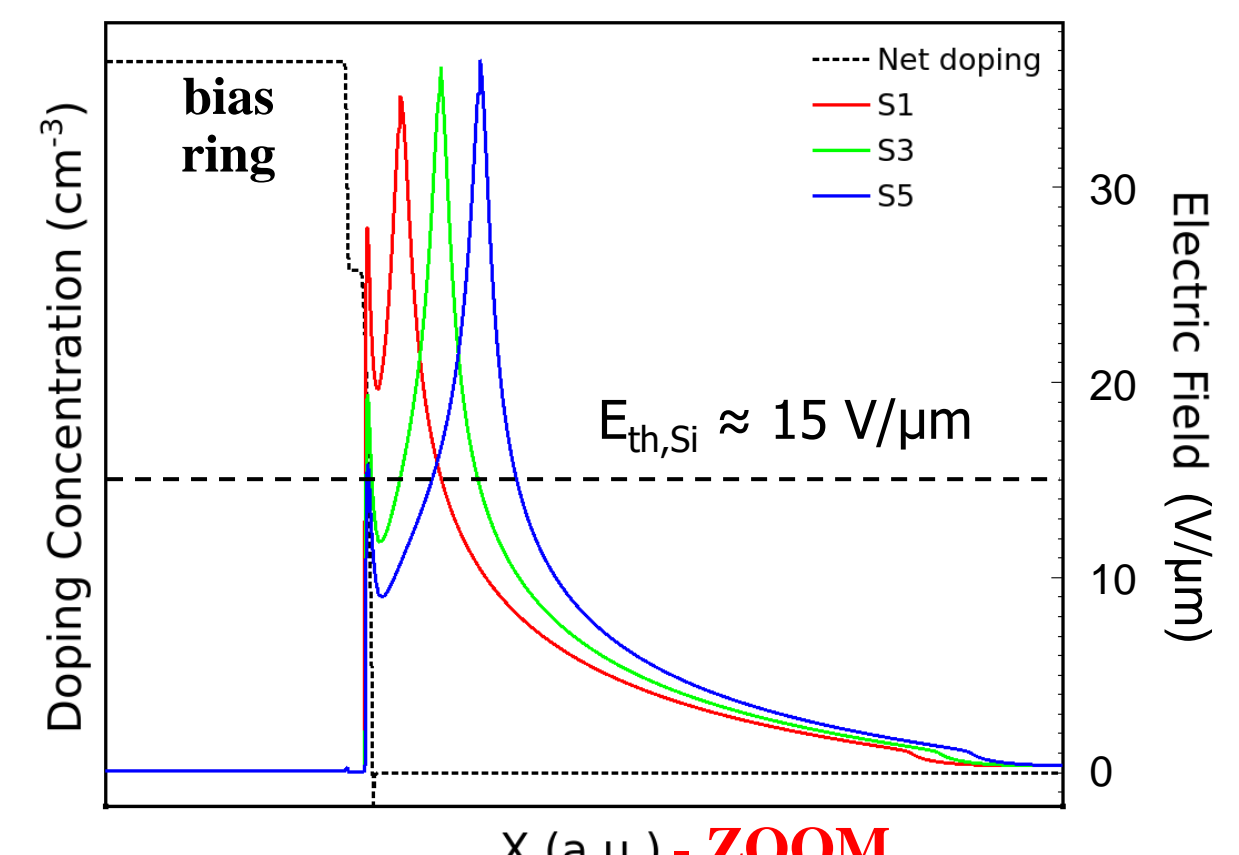
- ✓ GR0: no floating GRs, varying
 - metal overhang
- ✓ GR1: 1 floating GR, varying
 - floating GR position
 - metal overhang
- ✓ GR3: 3 floating GRs, using of:
 - single p-deep implant

Breakdown Voltage vs GR design

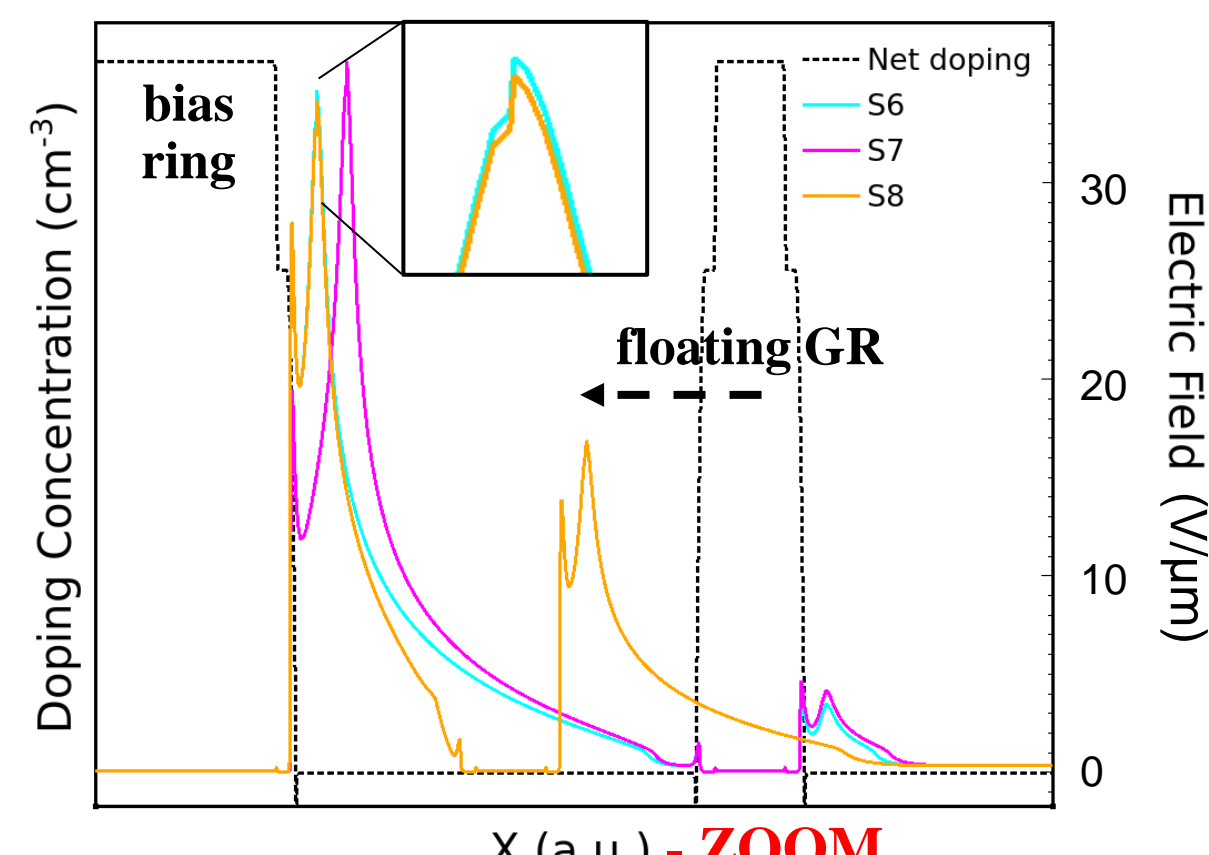


$V_{\text{BD},S3} \approx V_{\text{BD},S7} \approx V_{\text{BD},S10}$
 $V_{\text{BD},S1} \approx V_{\text{BD},S6}$
→ GR0 \approx GR1 \approx GR3
S5 worst GR design
S8 best GR design

GR0: Electric field @ breakdown



GR1: Electric field @ breakdown



Outcome

- ✓ The I-V characteristics and breakdown voltages of different Guard-Ring protection structures coming from the "EXFLU1" R&D batch (FBK) under different operating conditions (i.e. T and Φ) have been well reproduced in simulation [1].
- ✓ Use of the validated "Perugia Modified Doping" TCAD model [2] for a new series of simulations on different GR design strategies optimised for 55 μm -thick n-type substrates.
 - Ongoing sensor production, "NLGAD" R&D batch (FBK).
- ✓ The GR structures without any floating GR (i.e. GR0) have shown almost the same breakdown voltage of the GR1 and GR3 design options before and after irradiation.
 - GR structures without any floating GR are a viable design option.
- ✓ P-type substrate:
 - ✓ An improvement of the breakdown voltage in GR0 structures has been obtained by increasing the overhang size of the metal contact over the bias ring.
 - ✓ Almost all the GR structures show popcorn noise near the breakdown voltage and beyond the SEB limit [3], both before and after irradiation.
- ✓ N-type substrate:
 - ✓ An improvement of the breakdown voltage in GR1 structures has been obtained by reducing the distance between floating GR and the bias ring.

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DUTS

TCAD modelling

DUTS

TCAD modelling

V_{BD}

Electric field

Setup

V_{BD}

Popcorn noise